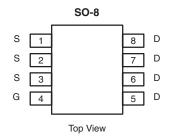


APM9428KC-TRL-VB Datasheet N-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)			
20	0.0049 at V _{GS} = 4.5 V	20 ^e	27.5 nC			
20	0.0056 at V _{GS} = 2.5 V	20 ^e	27.5110			



FEATURES

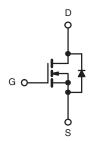
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_q and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



FREE

APPLICATIONS

- Low-Side MOSFET for Synchronous Buck
 - Game Machine
 - PC



N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	20	V	
Gate-Source Voltage		V_{GS}	± 16	7 v	
	T _C = 25 °C		20 ^e		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	l _D	18.2		
Sommer Surrom (1) = 100 0)	T _A = 25 °C] ^{'U} [15.2 ^{b, c}		
	T _A = 70 °C	1	12.1 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	50	7	
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	5.1		
Continuous Source-Diam Diode Current	T _A = 25 °C		2.2 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	30		
Avalanche Energy		E _{AS}	45	mJ	
	T _C = 25 °C		5.7		
Maximum Bayer Dissination	T _C = 70 °C	P _D	3.6	w	
Maximum Power Dissipation	T _A = 25 °C		2.5 ^{b, c}	¬ ~ ~	
	T _A = 70 °C	1	1.6 ^{b, c}		
Operating Junction and Storage Temperatur	e Range	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R_{thJA}	39	50	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	18	22	O/ V V		

Notes:

- a. Based on T_C = 25 °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 85 °C/W.
- e. Package limited.



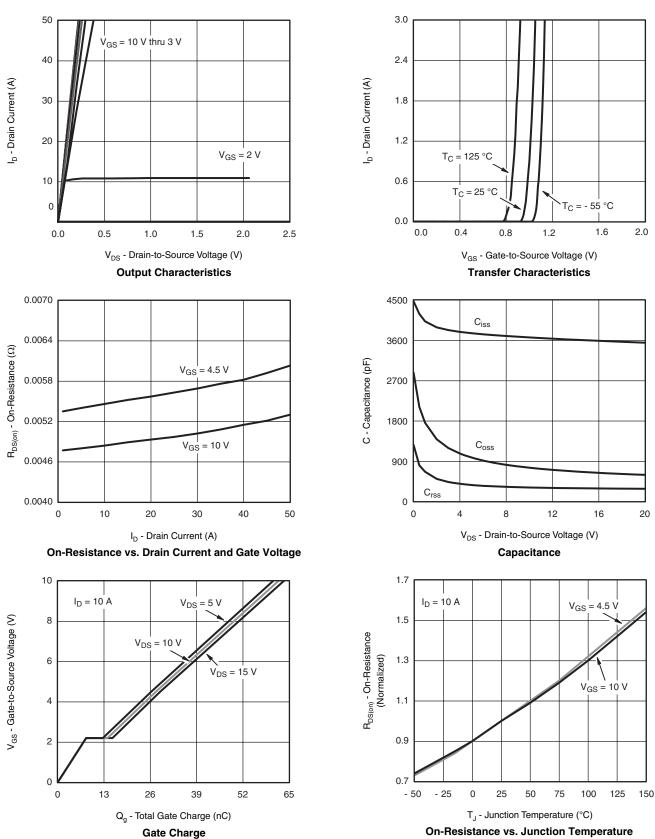
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	_				L		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J. 050A		19		>1/06	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$		- 5.3		mV/°0	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1.0		2.1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$			± 100	nA	
7 0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		V _{DS} = 20 V, V _{GS} = 0 V			1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
		$V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		0.0049	1		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 7 \text{ A}$		0.0056		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 10 A		55		S	
Dynamic ^b			I		L		
Input Capacitance	C _{iss}			3700		pF	
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		745			
Reverse Transfer Capacitance	C _{rss}			315			
Tabal Cada Obanas		$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		62	95	nC	
Total Gate Charge	Q_{g}	Q _g		27.5	42		
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		8.0			
Gate-Drain Charge	Q _{gd}			6.0			
Gate Resistance	R_g	f = 1 MHz	0.15	0.7	1.4	Ω	
Turn-On Delay Time	t _{d(on)}			30	55		
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_L = 2 \Omega$		13	25		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 5$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		60	100		
Fall Time	t _f			30	55		
Turn-On Delay Time	t _{d(on)}			13	25	ns	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2 Ω		9	18		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 5$ A, $V_{GEN}=10$ V, $R_g=1$ Ω		38	65		
Fall Time	t _f			8	16		
Drain-Source Body Diode Characterist	cs						
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			5.1		
Pulse Diode Forward Current ^a	I _{SM}				50	A	
Body Diode Voltage	V_{SD}	I _S = 2 A		0.71	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			26	50	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 10 A dl/dt = 100 A/vo T = 25 °C		16	30	nC	
Reverse Recovery Fall Time	t _a	I _F = 10 A, dl/dt = 100 A/μs, T _J = 25 °C		13			
Reverse Recovery Rise Time	t _b			13		ns	

Notes:

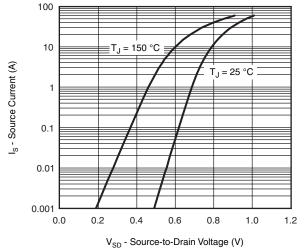
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

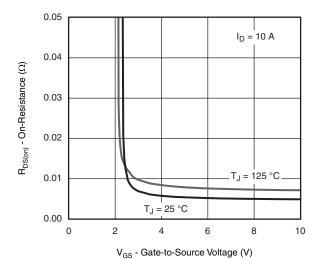




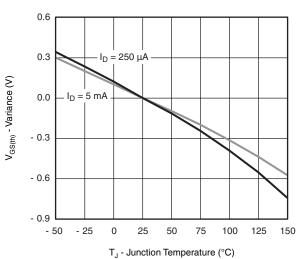




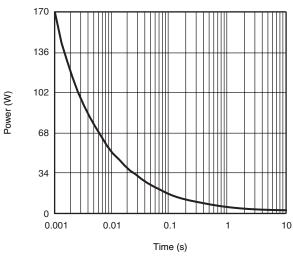
Source-Drain Diode Forward Voltage



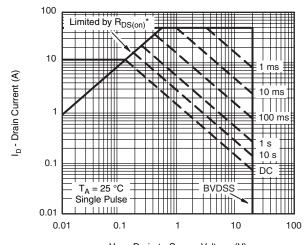
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



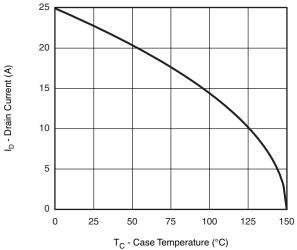
Single Pulse Power, Junction-to-Ambient



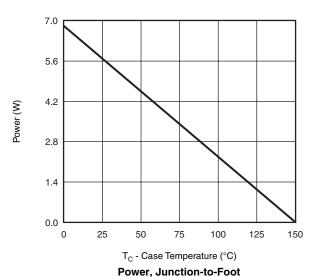
 $\rm V_{DS}$ - Drain-to-Source Voltage (V) * $\rm V_{DS}$ > minimum $\rm V_{GS}$ at which $\rm R_{DS(on)}$ is specified

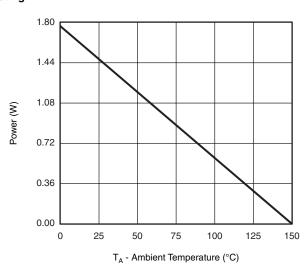
Safe Operating Area, Junction-to-Ambient





Current Derating*

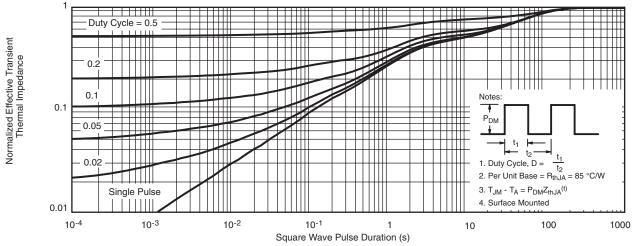




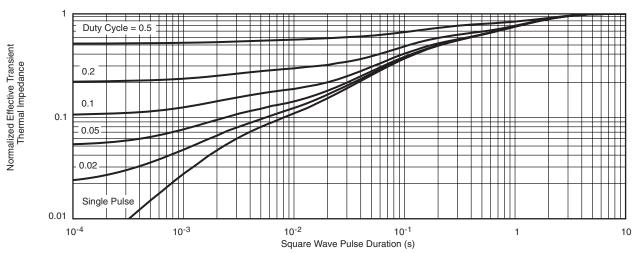
Power, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





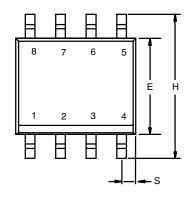
Normalized Thermal Transient Impedance, Junction-to-Ambient

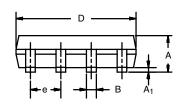


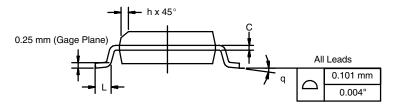
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





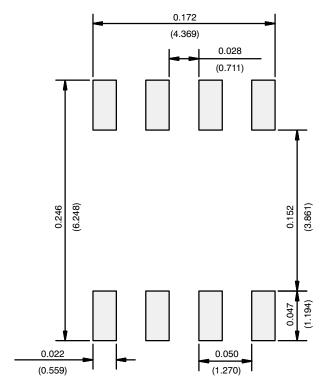


	MILLIM	IETERS	INC	INCHES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06						

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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